



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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DZ5S120D0R

DZ5S120D0R  
 Silicon epitaxial planar type

For surge absorption circuit  
 DZ5J120D in SSMINI5 type package

■ Features

- Excellent rising characteristics of zener current I<sub>Z</sub>
- Low zener operating resistance R<sub>Z</sub>
- Halogen-free / RoHS compliant  
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol:05

■ Basic Part Number :

Dual DZ3X120D (Common anode)

■ Packaging

Embossed type (Thermo-compression sealing) 8 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

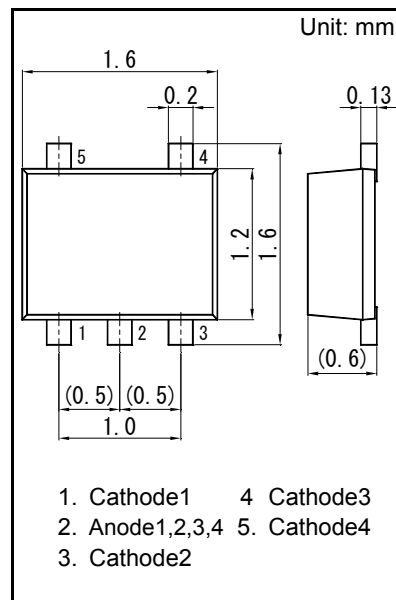
Parameter	Symbol	Rating	Unit
Total power dissipation <sup>*1</sup>	PT	150	mW
Electrostatic discharge <sup>*2</sup>	ESD	±10	kV
Junction temperature	T <sub>j</sub>	150	°C
Operating ambient temperature	T <sub>opr</sub>	-40 to +85	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

Note) \*1: Mounted on glass epoxy print board. ( 45 mm x 45 mm x 1 mm)

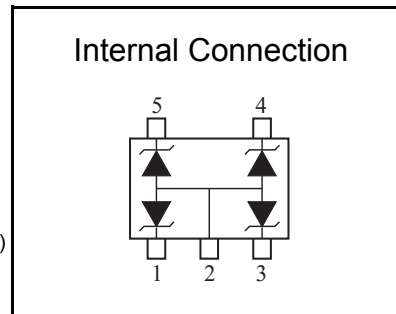
(4Diode total)

Solder in ( 0.35 mm x 0.40 mm)

\*2: Test method:IEC61000\_4\_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)



Panasonic	SSMini5-F4-B
JEITA	SC-107BB
Code	SOT-665



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 10 mA			1.0	V
Zener voltage <sup>*1, *2</sup>	V <sub>Z</sub>	I <sub>Z</sub> = 5 mA	11.40		12.60	V
Zener operating resistance	R <sub>Z</sub>	I <sub>Z</sub> = 5 mA			30	Ω
Zener rise operating resistance	R <sub>ZK</sub>	I <sub>Z</sub> = 0.5 mA			80	Ω
Reverse current	I <sub>R</sub>	V <sub>R</sub> = 9 V			0.05	μA
Temperature coefficient of zener voltage <sup>*3</sup>	SZ	I <sub>Z</sub> = 5 mA		8.5		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

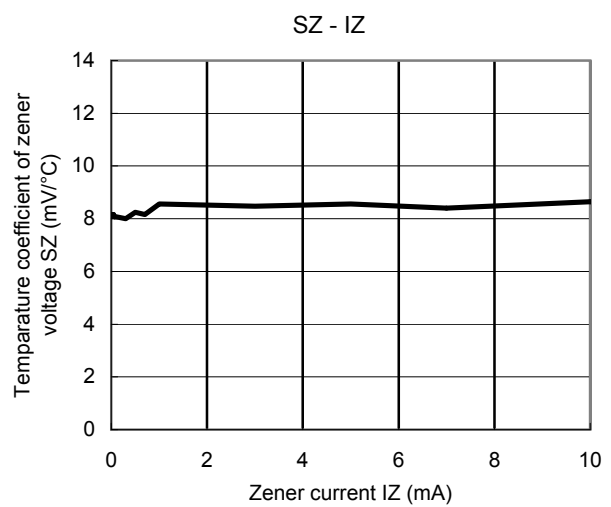
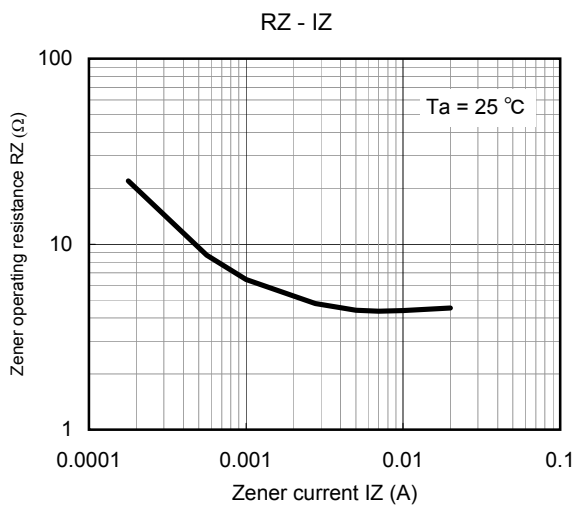
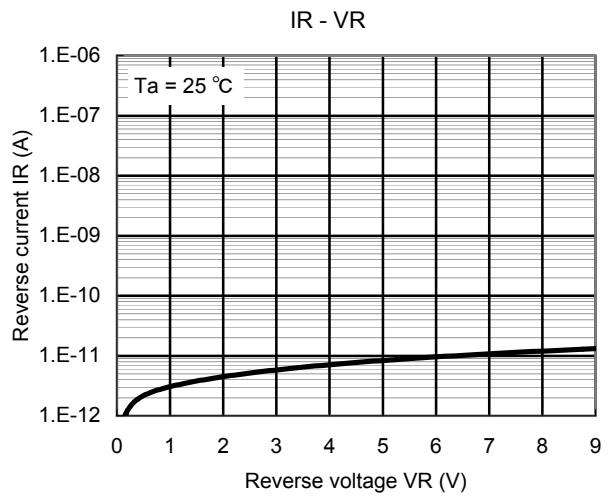
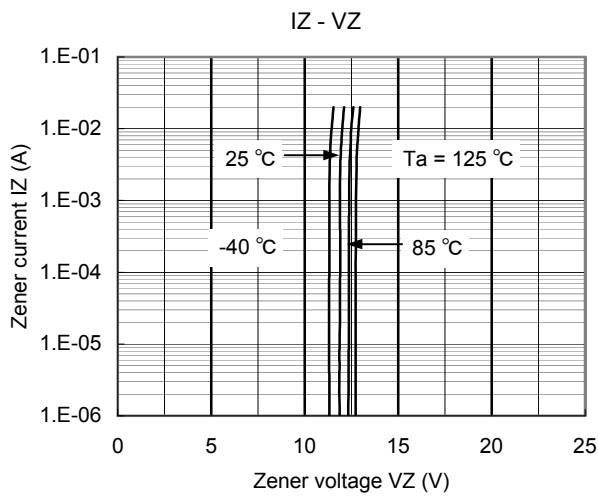
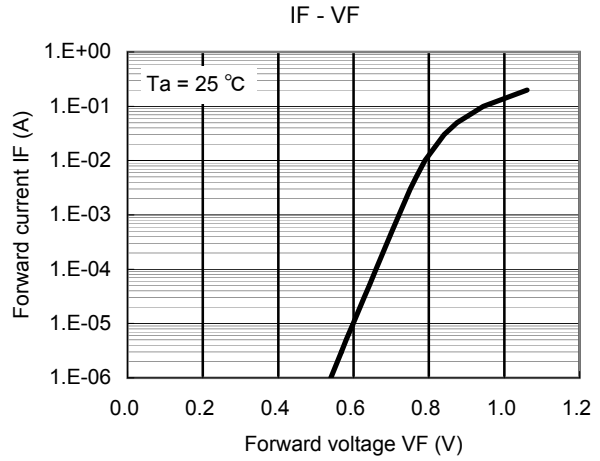
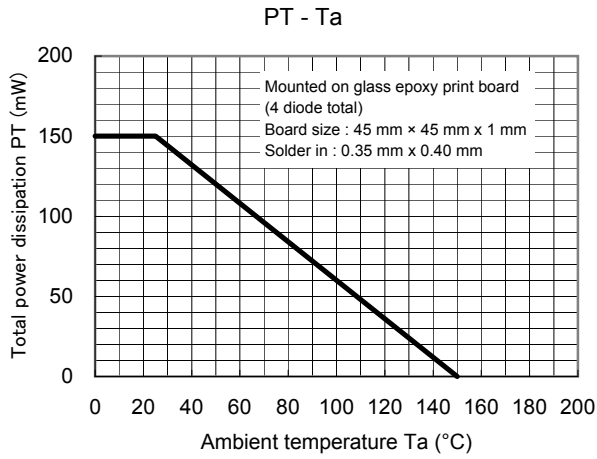
2. \*1: The temperature must be controlled 25°C for V<sub>Z</sub> measurement.

V<sub>Z</sub> value measured at other temperature must be adjusted to V<sub>Z</sub> (25°C)

\*2: V<sub>Z</sub> guaranteed 20 ms after current flow.

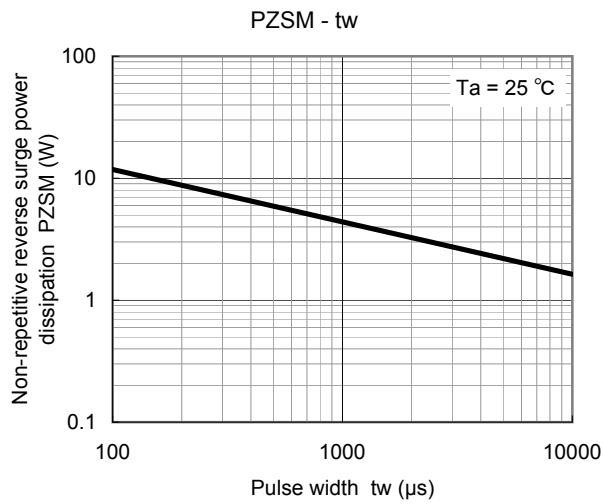
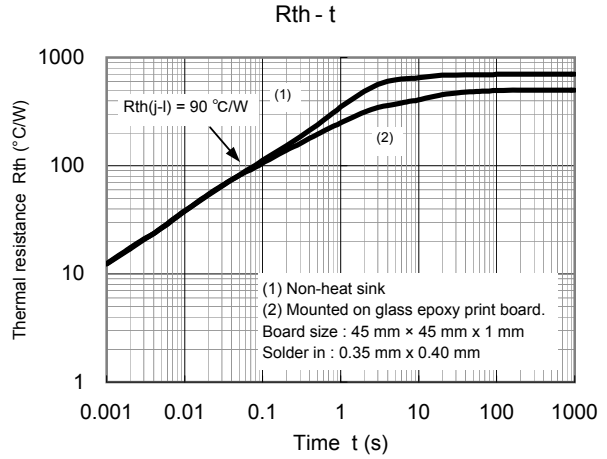
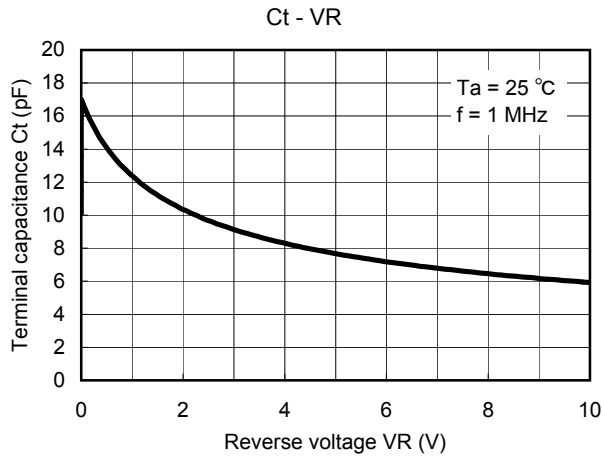
\*3: T<sub>j</sub> = 25°C to 150°C

Technical Data ( reference )



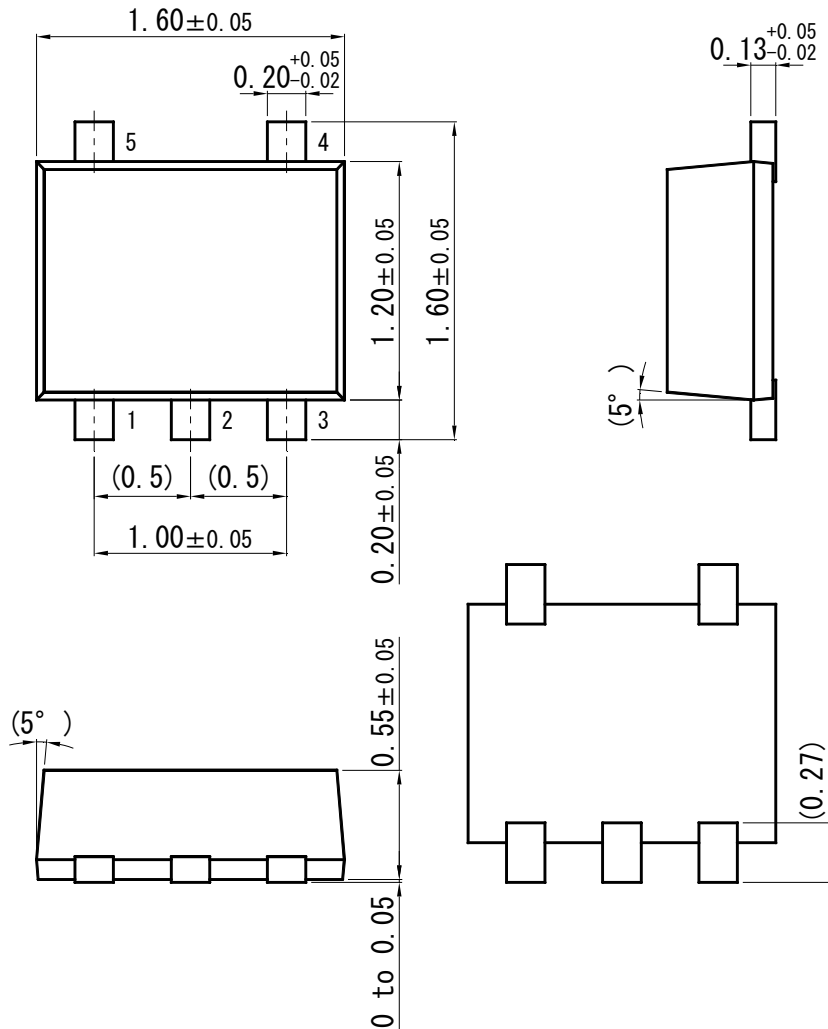


Technical Data ( reference )

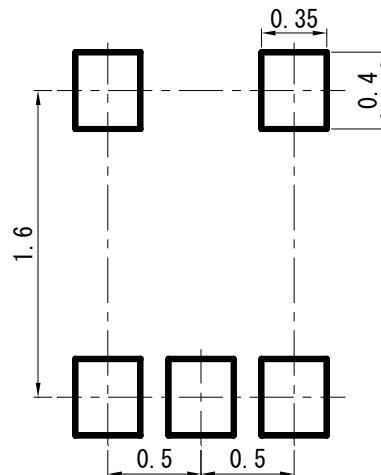


**SSMini5-F4-B**

Unit: mm



■ Land Pattern (Reference) (Unit: mm)





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